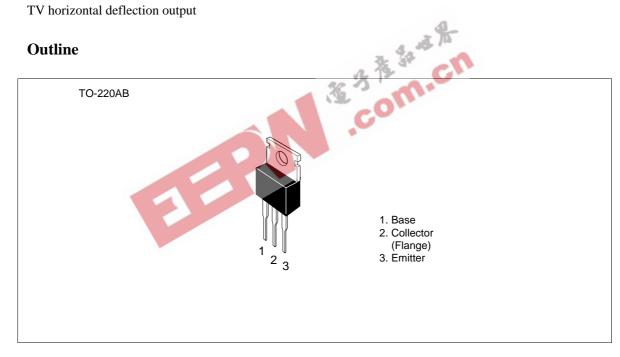
Silicon NPN Triple Diffused

HITACHI

Application

TV horizontal deflection output

Outline





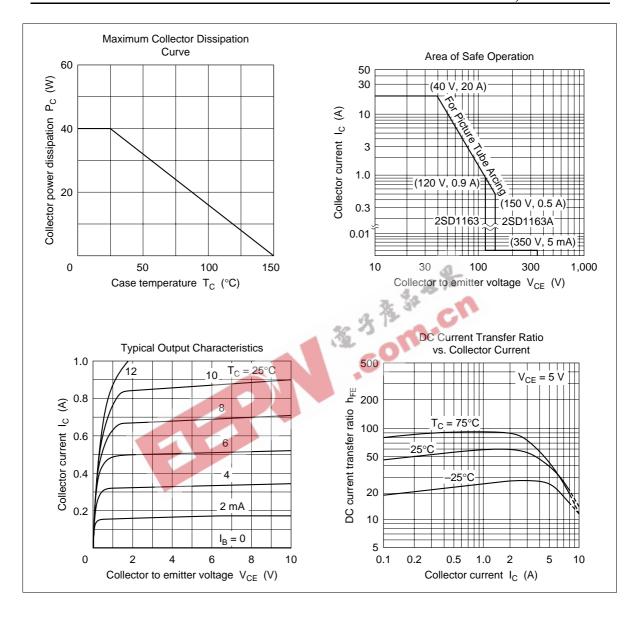
Absolute Maximum Ratings (Ta = 25°C)

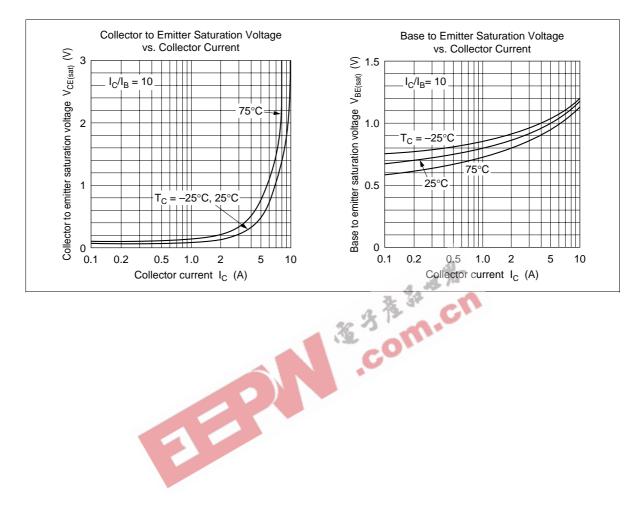
		Rating			
Item	Symbol	2SD1163	2SD1163A	Unit	
Collector to base voltage	V_{CBO}	300	350	V	
Collector to emitter voltage	V_{CEO}	120	150	V	
Emitter to base voltage	V_{EBO}	6	6	V	
Collector current	I _c	7	7	Α	
Collector peak current	C (peak)	10	10	А	
Collector surge current	C (surge)	20	20	А	
Collector power dissipation	P _c *1	40	40	W	
Junction temperature	Tj	150	150	°C	
Storage temperature	Tstg	-55 to +150	-55 to +150	°C	

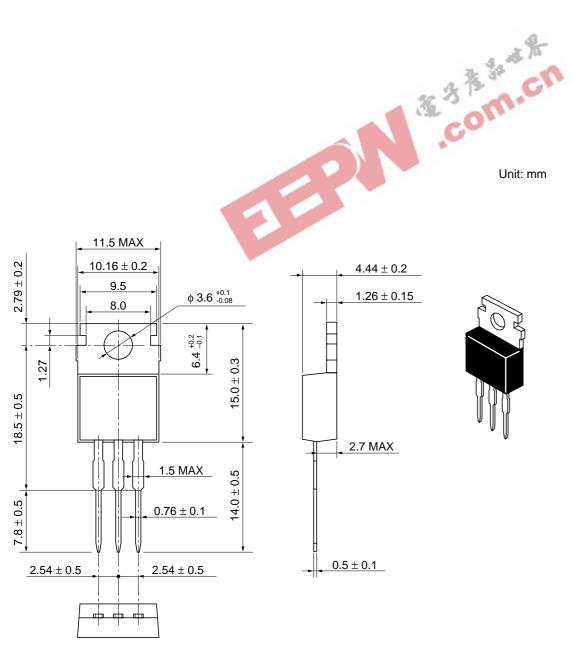
	28	D1	163		2SD1	163A
_	 					

Storage temperature		Tstg -55 to +150 -55 to +150 °C				o +150 °C			
Note: 1. Value at $T_c = 25^{\circ}C$. Electrical Characteristics ($Ta = 25^{\circ}C$)									
		2SD1	163		2SD1163A				
Item	Symbol	Min	Тур	Max	Min	Тур	Max	Unit	Test conditions
Collector cutoff current	I _{CBO}		_	5	_	_	_	mΑ	$V_{CB} = 300 \text{ V}, I_{E} = 0$
			_	_	_	_	5	mΑ	$V_{CB} = 350 \text{ V}, I_{E} = 0$
Collector to emitter breakdown voltage	V _{(BR)CEO}	120	_	_	150	_	_	V	$I_{\rm C}$ = 10 mA, $R_{\rm BE}$ = ∞
Emitter to base breakdown voltage	$V_{(BR)EBO}$	6	_	_	6	_	_	V	$I_{E} = 10 \text{ mA}, I_{C} = 0$
DC current transfer ratio	h _{FE}	25	_	_	25	_	_		$V_{CE} = 5 \text{ V}, I_{C} = 5 \text{ A}^{*1}$
Collector to emitter saturation voltage	V _{CE (sat)}	_	_	2.0	_	_	1.0	V	$I_{\rm C} = 5 \text{ A}, I_{\rm B} = 0.5 \text{ A}^{*1}$
Base to emitter saturation voltage	V _{BE (sat)}	_	_	1.2	_	_	1.2	V	$I_{\rm C} = 5 \text{ A}, I_{\rm B} = 0.5 \text{ A}^{*1}$
Fall time	t _f	_	_	0.5	-	_	0.5	μs	$I_{CP} = 3.5 \text{ A},$ $I_{B1} = 0.45 \text{ A}$

Note: 1. Pulse test.







Hitachi Code	TO-220AB
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	1 8 a

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